Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ($L^2-\pi$ -MOSV)

2SK2745

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4 V gate drive

• Low drain-source ON resistance : $RDS(ON) = 7.0 \text{ m}\Omega \text{ (typ.)}$

• High forward transfer admittance : $|Y_{fs}| = 50 \text{ S (typ.)}$

• Low leakage current : $I_{DSS} = 100 \mu A \text{ (max)} \text{ (V}_{DS} = 50 \text{ V)}$

• Enhancement-mode : $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	50	V	
Drain-gate voltage (R	_{GS} = 20 kΩ)	V_{DGR}	50	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	50	Α	
Diain current	Pulse (Note 1)	I _{DP}	200	Α	
Drain power dissipatio	n (Tc = 25°C)	P_{D}	150	W	
Single pulse avalanche	e energy (Note 2)	E _{AS}	747	mJ	
Avalanche current		I _{AR}	50	Α	
Repetitive avalanche	energy (Note 3)	E _{AR}	15	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature r	ange	T _{stg}	-55~150	°C	

Weight: 4.6 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	0.833	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 25 V, T_{ch} = 25 °C (initial), L = 368 μ H, R_{G} = 25 Ω , I_{AR} = 50 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.



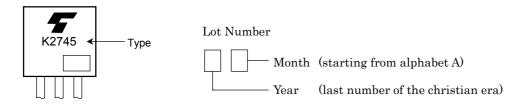
Electrical Characteristics (Ta = 25°C)

Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cui	rrent	I _{DSS}	V _{DS} = 50 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	50	_	_	V
Gate threshold v	oltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 4 V, I _D = 25 A	_	11	16	- mΩ
			V _{GS} = 10 V, I _D = 25 A	_	7	9.5	
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 25 A	30	50	_	S
Input capacitano	e	C _{iss}		_	4000	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		800	_	pF
Output capacitance		Coss			2000	_	
Switching time	Rise time	t _r	V_{GS} V_{OV} V_{DD} V_{DD} V_{DD}	_	25	_	- ns
	Turn-on time	t _{on}		_	40	_	
	Fall time	t _f		ı	120		
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\rm w} = 10 \mu \rm s$	_	360	_	
Total gate charge (gate-source plus gate-drain)		Q_{g}		_	130	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 40 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		90	_	nC
Gate-drain ("miller") Charge		Q _{gd}			40	_	

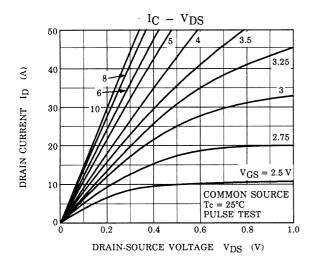
Source-Drain Ratings and Characteristics (Ta = 25°C)

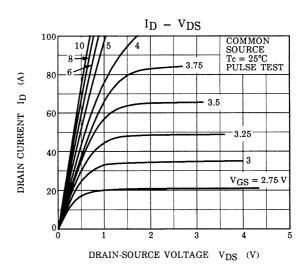
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	50	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-	_	_	200	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 50 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 50 A, V _{GS} = 0 V, dI _{DR} / dt = 50 A / μs	_	140	_	ns
Reverse recovery charge	Q _{rr}	1DR - 30 Λ, VGS - 0 V, αιDR / αι - 30 Λ / μs	_	80	_	μC

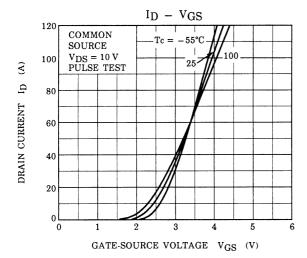
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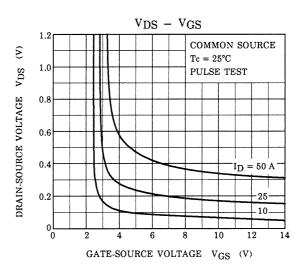


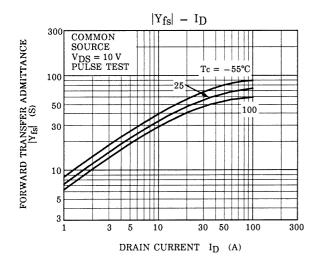
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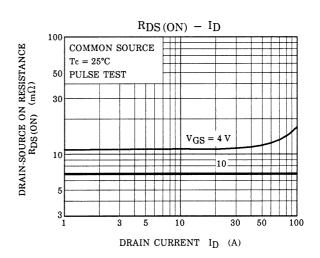




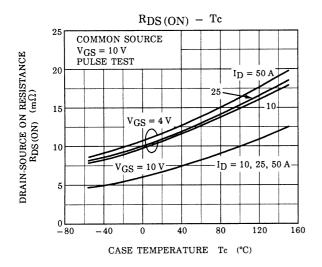


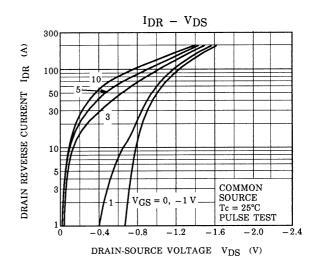


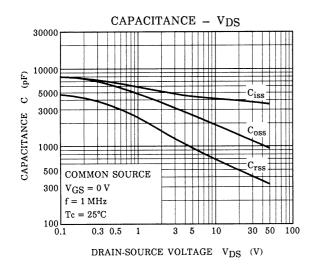


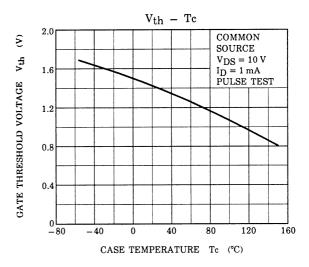


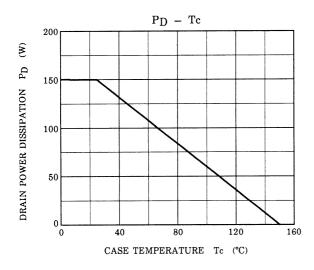
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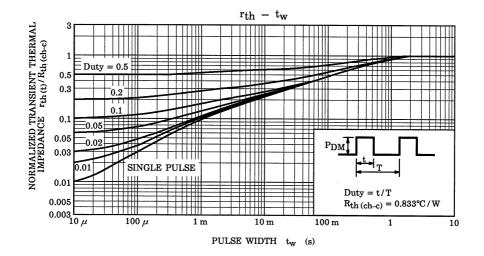


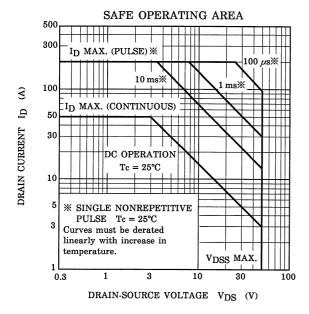


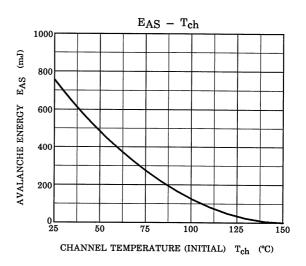


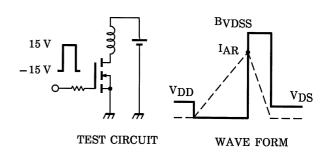


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$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 25~V,~L = 368~\mu H \end{aligned} \qquad E_{AS} &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right) \end{aligned}$$

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